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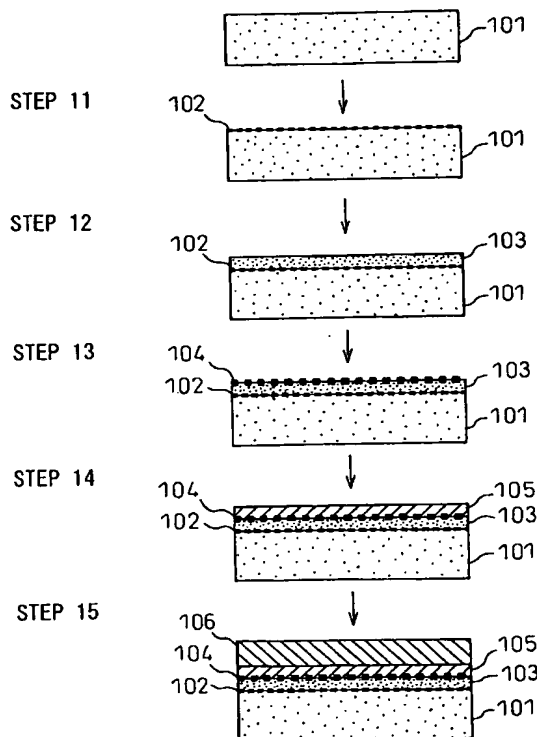
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(54) Title: POLYIMIDE-METAL LAMINATED BODY AND POLYIMIDE CIRCUIT BOARD



(57) Abstract: A polyimide-metal laminated body obtained by forming a metal conductive layer on a polyimide film, which has been ceramic-modified or pseudoceramic-modified on at least the surface, by a wet plating process capable of accomplishing metal plating on ceramic. A polyimide-metal laminated body and polyimide circuit board having satisfactory cohesion in wet plating steps, maintain practical cohesion even after high temperature aging treatment, and exhibiting satisfactory electrical insulating reliability, can be obtained.

WO 2005/068185 A1



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